ABSTRACT

METHOD FOR FABRICATING SEMICONDUCTOR PACKAGES, AND LEADFRAME ASSEMBLIES FOR THE FABRICATION THEREOF

A method for fabricating semiconductor packages provides a leadframe for packages that are to be singulated with respective predetermined package body sizes. Individual mold caps are formed on the leadframe with mold cap dimensions that are larger than the respective predetermined package body sizes. The mold caps and leadframe are sawed to singulate packages therefrom. The sawing reduces the dimensions of the mold caps to the respective predetermined package body sizes. (Fig. 8)